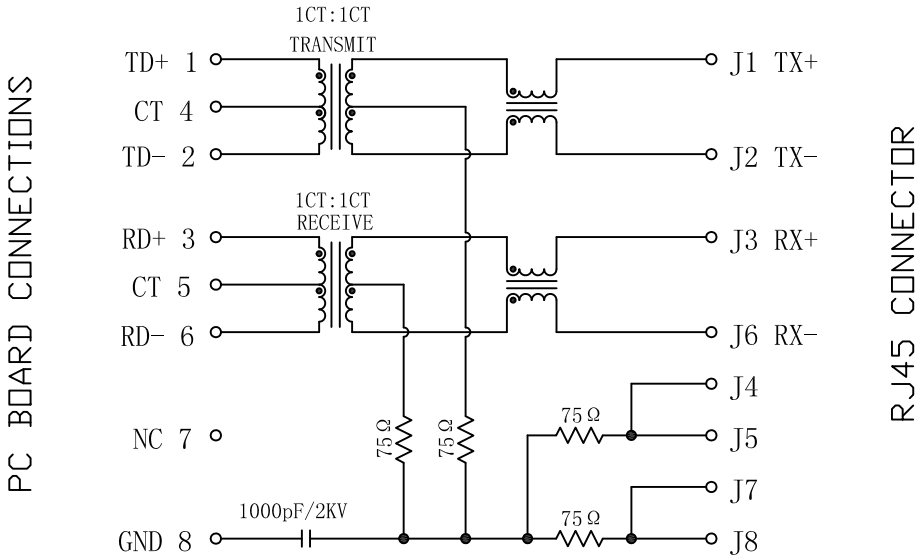
Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2010-03-20	



ELECTRICAL SPECFICATIONS @25℃

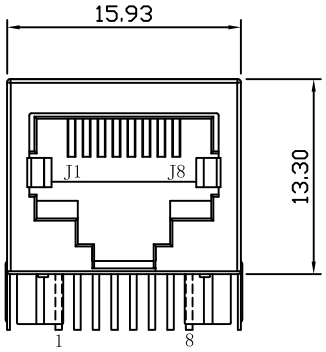
1. Turn Ratio(±2%):
   TX=1CT:1CT RX=1CT:1CT
2. Inductance OCL: 350uH MIN
   @100KHz/0.1V,8mA DC Bias
3. Insertion Loss:
   -1.0dB MAX @ 1.0-65MHz
4. Return Loss:
   -20dB MIN @ 1-10MHz
   -16dB MIN @ 10-30MHz
   -12dB MIN @ 30-60MHz
   -10dB MIN @ 60-100MHz
5. Cross talk:
   -40dB MIN @ 1-30MHz
   -35dB MIN @ 30-60MHz
   -30dB MIN @ 60-100MHz
6. Common Mode Rejection:
   -30dB MIN @ 1-50MHz
   -20dB MIN @ 50-150MHz
7. Hipot Test: 1500Vrms MIN
8. Operating Temperature: -40℃ TO +85℃.

RoHS 2011/65/EU

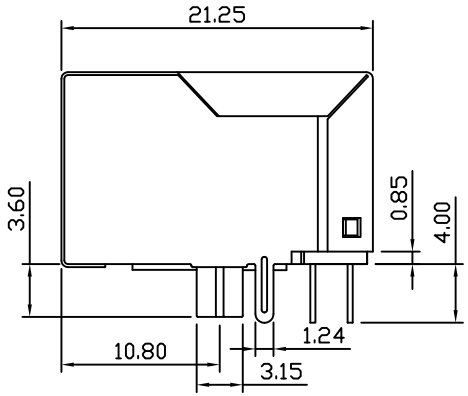
X:X ±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX ±0.25	CHKD:	TITLE: RJ45 Connector with 10/100 Base-T Integrated Magnetics	
X:XXX ±0.05	DR: TOM		
ANGLES ±1°	UNIT: mm	PART NO.: LPJ4011DNL	
	SCALE: 2/1	SHEET: 1/2	REV: A	DWG NO.: LP10032011

Mechanical:

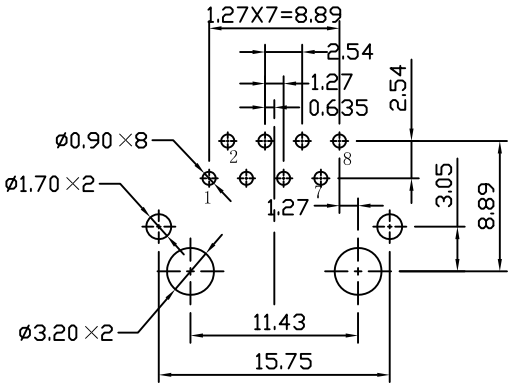
REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2010-03-20	



Front Side View

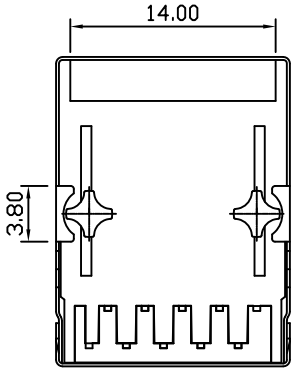


Left Side View

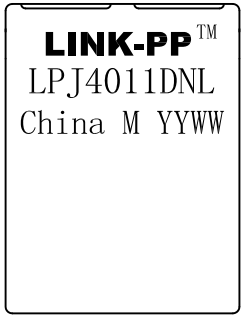


Suggested PCB Layout(Top View)

RoHS
2011/65/EU



Bottow Side View



Top Side View

NOTES:

1. Designed to support application, such as SOHO(ADSL modems), LAN-on-Motherboard(LOM), hub and Switches.
2. Meets IEEE 802.3 specification
3. Connector Materials:
   Housing: Thermoplastic PBT+30%G.F UL94V-0
   Contact: Phosphor Bonze C5210R-EH Thickness=0.35mm
   Pins: Brass C2680R-H Thickness=0.35mm
   Shield: SUS 201-1/2H Thickness=0.2mm
   Contact plating: Gold 6 micro-inches min. In contact area.
4. Wave solder tip temperature: 265℃ Max, 5 Sec Max.

X:X ±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX ±0.25	CHKD:	TITLE: RJ45 Connector with 10/100 Base-T Integrated Magnetics	
X:XXX ±0.05	DR: TOM		
ANGLES ±1°	UNIT: mm	PART NO.: LPJ4011DNL	
	SCALE: 2/1	SHEET: 2/2	REV: A	DWG NO.: LP10032011